

賀！化材系學生

參加台灣電路板協會TPCA 2023 PCB 學生優秀論文獎
蔣瑛芷榮獲金獎、林鈺銘榮獲銀獎

2023 PCB 學生優秀論文獎 狂賀！元智大學蔣瑛芷同學榮獲 2023 PCB 學生優秀論文—金獎！

PCB Student Best Paper Award Congratulations to YING-CHIH CHIANG, student from Yuan Ze University, winning the top prize of the 2023 PCB Student Best Paper Award!

PCB 學生優秀論文獎舉辦多屆，年年吸引各校菁英爭相投稿，歷經摘要初選及全文複選兩輪評比後，從中拔擢出最符合低碳轉型，並具備產業應用性的論文，由元智大學的蔣瑛芷同學摘冠，以「Quantitative Characterization of High-speed Signal Transmission Performance in Eco-friendly Multilayer PCBs with Different Via Stub Lengths」一文榮獲金獎；同樣來自元智大學

的林鈺銘同學，則是以「Improving Uniformity of Electroplated Cu for TGV Metallization」一文獲得銀獎。得獎學生論文精彩內容，歡迎至 TPCA Show 優秀論文攤位處瀏覽。金獎、銀獎之學生除獲得高獎外，更可獲得海外參展專案補助！於 2024 年前往美國參與第 16 屆世界電子電路大會-ECWC16，進行得獎論文英文發表與展會參訪。感謝企業對產學推動不遺餘力，共同為

台灣 PCB 產業升級努力。特別感謝大量科技、宇泰和公司、尖點科技、迅得機械、欣興電子、興普科技等六家企業的熱情贊助

This highly competitive and prestigious award is given only to the most outstanding applicants. Through primary and secondary review by professors from the industry, select papers that are the best for low-carbon transformation and have industrial application. The final winners were determined for the Student Best Paper Award this year. Congratulations to Ying-Chih Chiang, student from Yuan Ze University, who won the Gold Award with paper titled "Quantitative Characterization of High-speed Signal Transmission Performance in Eco-friendly Multilayer PCBs with Different Via Stub Lengths."

In addition, Yu-Ming Lin, student also from Yuan Ze University, won

the Silver Award with paper titled, "Improving Uniformity of Electroplated Cu for TGV Metallization." For the detailed content of the outstanding papers from the winning students, please refer to Best Paper Poster Booth during TPCA Show 2023.

In addition to high bonuses, Gold and Silver Award students will also have the opportunity to receive subsidies to publish papers at ECWC16 and visit exhibitions. Thanks the sponsors for their tireless efforts to promote industry and academia, and work together to upgrade Taiwan's PCB industry.

This award also gives special thanks to the following sponsors: Taliang Technology, U-Pro Machines, Topoint Technology, Symtek Automation Asia, Unimicron and Shin Puu Technology.

獎別 Prize	論文題目 Paper Topic	作者 Author	指導教授 Professor	學校 School	IMAPCT 發表場次 Session
金獎 Gold Prize	Quantitative Characterization of High-speed Signal Transmission Performance in Eco-friendly Multilayer PCBs with Different Via Stub Lengths	蔣瑛芷 Ying-Chih Chiang	何政恩 Cheng-En Ho	元智大學 Yuan Ze University	Session 26
銀獎 Silver Prize	Improving Uniformity of Electroplated Cu for TGV Metallization	林鈺銘 Yu-Ming Lin	何政恩 Cheng-En Ho	元智大學 Yuan Ze University	Session 19

賀！化材系郭許宏同學 參加創新與永續科技國際研討會 榮獲壁報論文競賽優選



賀！化材系何政恩教授 榮獲第19屆徐有庠基金會 有庠元智講座教授



何政恩 教授

兼任研究發展處副研發長、產學合作組組長

研究專長

1. 三維積體電路封裝
2. 相平衡與界面反應
3. 電遷移
4. 無鉛錒料
5. 同步輻射微區繞射
6. 電鍍銅填孔